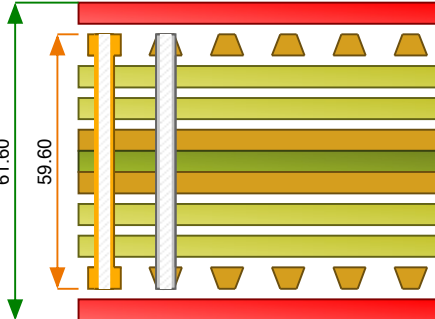



Layer	Stack up	Description	Processed Thickness	Isolation Distance (Summed)	Copper Coverage	εr	Impedance ID		
1		ELECTRA EMP 110/5410- RED	1.000			4.000			
		Copper Foil 12 microns	1.850		100.000		1, 2, 3		
		Iteq IT180A Prepreg 1080 RC65-NEW	2.315	4.630		3.860			
		Iteq IT180A Prepreg 1080 RC65-NEW	2.315	-		3.860			
2			2.638		51.000				
		Iteq IT180A 47 mil core 2/2	41.600	41.600		3.770			
3			2.638		42.000				
		Iteq IT180A Prepreg 1080 RC65-NEW	2.196	4.392		3.860			
4			Iteq IT180A Prepreg 1080 RC65-NEW	2.196	-		3.860		
		Copper Foil 12 microns	1.850		100.000		4, 5, 6		
	ELECTRA EMP 110/5410- RED	1.000			4.000				

Copper Thickness = 8.977 | Dielectric Thickness = 50.622 | Solder Mask Thickness = 2.000 | Stack Up Thickness = 59.599 | Stack Up Thickness with Soldermask = 61.599

Impedance ID	Impedance Signal Layer	Structure Name	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	
1	1	Coated Microstrip 1B	2	0	5.900	0.000	0.000	56.170	50.000	10.000	
2	1	Edge Coupled Coated Microstrip 1B	2	0	4.500	4.500	0.000	94.200	90.000	10.000	
3	1	Edge Coupled Coated Microstrip 1B	2	0	4.000	6.000	0.000	105.900	100.000	10.000	
4	4	Coated Microstrip 1B	3	0	5.900	0.000	0.000	54.600	50.000	10.000	
5	4	Edge Coupled Coated Microstrip 1B	3	0	4.500	4.500	0.000	93.000	90.000	10.000	
6	4	Edge Coupled Coated Microstrip 1B	3	0	4.000	6.000	0.000	104.420	100.000	10.000	

Notes

StackName: MISTRAL-PROC177 REV B[CAM#59840]-A00	Version:	Revision:	Modification:	Date of Revision:	Editor	Pag	
Date: 14-12-2023	Associated Documents:	1		14-12-2023	HARIPRASAD		
Author: -	F14122023-59840-A00						
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